

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hyodo, et al.
Appl. No. : 10/644,195
Filed : August 20, 2003
For : METHOD OF FORMING
SILICON-CONTAINING
INSULATION FILM HAVING
LOW DIELECTRIC CONSTANT
AND LOW FILM STRESS
Examiner : David S Blum
Group Art Unit : 2813

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed March 28, 2006, please reconsider the present application in light of the following amendments and comments.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.